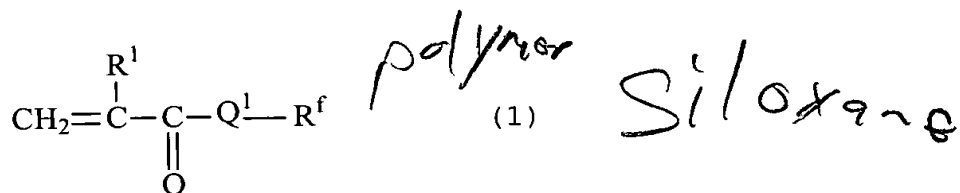


Polymer units (b¹): Polymer units derived from a compound containing a silicon atom and an unsaturated group.

16. (New) The composition according to Claim 15, wherein the polymer units (a¹) are polymer units derived from a compound represented by the following formula (1):



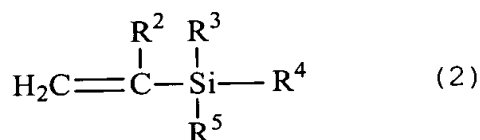
provided that in the formula (1), Q¹, R¹ and R^f have the following meanings.

Q¹: A single bond or a bivalent connecting group.

R¹: A hydrogen atom or a methyl group.

R^f: A polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond.

17. (New) The composition according to Claim 15, the polymer unit (b¹) is a polymer unit of the compound having the following formula (2):



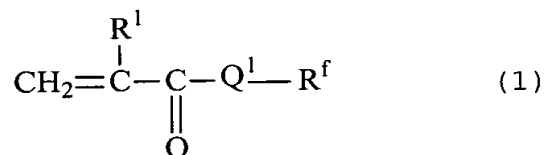
provided that in the formula (2), R², R³, R⁴ and R⁵ have the following meanings.

R²: A hydrogen atom or a methyl group.

R³, R⁴ and R⁵: Independently from one another, an alkyl group having a carbon number of from 1 to 5, or an alkoxy group having a carbon number of from 1 to 5.

18. (New) A composition for preventing creeping of a flux for soldering, which comprises a polymer (A) containing the following polymer units (a¹) and the following polymer units (b¹), and an aqueous medium (B).

Polymer units (a¹): Polymer units derived from a compound represented by the following formula (1):



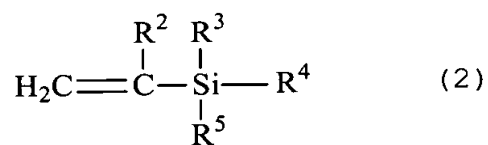
provided that in the formula (1), Q¹, R¹ and R^f have the following meanings.

Q¹: A single bond or a bivalent connecting group.

R¹: A hydrogen atom or a methyl group.

R^f: A polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond,

Polymer units (b¹): Polymer unit derived from a compound having the following formula (2):



provided that in the formula (2), R², R³, R⁴ and R⁵ have the following meanings.

R²: A hydrogen atom or a methyl group.

R³, R⁴ and R⁵: Independently from one another, an alkyl group having a carbon number of from 1 to 5, or an alkoxy group having a carbon number of from 1 to 5.

19. (New) The composition according to Claim 15, which further contains a fluorine type surfactant (C).

20. (New) The composition according to claim 15, wherein the softening point of the polymer (A) is at least 40°C and less than 150°C.

21. (New) The composition according to Claim 15, wherein the aqueous medium (B) contains a water-soluble organic solvent, and the boiling point of the water-soluble organic solvent is from 40 to 200°C.

22. (New) The composition according to Claim 15, wherein the surface tension of the composition is from 10 to 25 mN/m.

23. (New) The composition according to Claim 15, wherein the polymer (A) further contains polymer units (c¹) other than the polymer units (a¹) and the polymer units (b¹) and the polymer units (c¹) are derived from a monomer containing a polymerizable unsaturated group, no R^f group and no silicon atom.

24. (New) The composition according to Claim 16, wherein the polymer (A) further contains polymer units (c¹) other than the polymer units (a¹) and the polymer units (b¹) and the polymer units (c¹) are derived from a monomer containing a polymerizable unsaturated group, no R^f group and no silicon atom.

25. (New) The composition according to Claim 17, wherein the polymer (A) further contains polymer units (c¹) other than the polymer units (a¹) and the polymer units (b¹) and the polymer units (c¹) are derived from a monomer containing a polymerizable unsaturated group, no R^f group and no silicon atom.

26. (New) The composition according to Claim 18, wherein the polymer (A) further contains polymer units (c¹) other than the polymer units (a¹) and the polymer units (b¹) and

the polymer units (c¹) are derived from a monomer containing a polymerizable unsaturated group, no R^f group and no silicon atom.

27. (New) The composition according to Claim 23, wherein the polymer units (c¹) are polymer units derived from at least one monomer selected from the group consisting of ethylene, vinyl chloride, styrene, (meth)acrylic acid, cyclohexyl (meth)acrylate, an alkyl (meth)acrylate, a mono(meth)acrylate of a polyoxyalkylene diol and glycidyl (meth)acrylate.

28. (New). The composition according to Claim 23, wherein the polymer units (a¹) are polymer units derived from R^f-OCOCH=CH₂, the polymer units (b¹) are polymer units derived from CH₂=CHSi(OR⁶)₃, and the polymer units (c¹) are polymer units derived from cyclohexyl(meth)acrylate, wherein

R^f: A polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond and

R⁶: is an alkyl group having a carbon number of from 1 to 3.

29. (New) A method for soldering an electronic part or printed board which comprises forming a coating film of the composition as defined in Claim 15 on a part or the whole surface of an electronic part or a printed board, then treating the surface having the coating film thus formed, with a flux for soldering, and then carrying out soldering.

30. (New) A method for soldering an electronic part or printed board, which comprises forming a coating film of the composition as defined in Claim 23 on a part or the whole surface of an electronic part or a printed board, then treating the surface having the coating film thus formed, with a flux for soldering, and then carrying out soldering.

31. (New) A soldered electronic part or printed board, obtained by the method as defined in Claim 29.